

- To: Applications Group
- From: Peter Vaughan

Date: 14-Apr-16

Revision: B

Re: Minimum PCB spacing for spark gaps in adapter designs

Summary

- Minimum spark gap PCB creepage from AC input to secondary side (not primary to secondary where voltages can exceed the AC input)
 - $\circ~$ 5 mm for pollution degree 2 applications with PCB CTI in Material group III, 250 V_{RMS} working voltage
 - $\circ~$ 3.6 mm for pollution degree 2 applications with PCB CTI in Material group II, 250 V_{RMS} working voltage
 - Pollution degree 2 and 2,500 V Transient is appropriate for AC adapters.
 - Material group II PCB material (FR4 variant) is 3-5% more expensive than standard material
- Arcing voltage may be lower when using an in house milled PCB due to sharper edges across the spark gap. Validate critical designs using a production PCBs where etching process results in a smoother surface finish.

Parameter	Spacing (mm)	Pollution Degree	100% Electric Strength Testing	Mains Transient Voltage	
	4		No	1500 V	
Minimum Clearance	3	1, 2 or 3	Yes	or 2500 V	
	6.4	1,2013	No	4000 V	
	6.0		Yes	4000 V	
	5	2 (CTI Group III)		N/A	
Minimum Creepage	3.6	2 (CTI group II)	N/A		
	8	3			

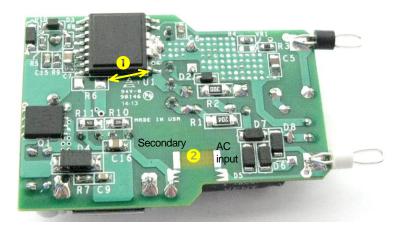
Description

The reliability of the spark gap firing before any other points is so critical this memo was created to record the verification that the spark gap spacing of 5 mm is acceptable for safety or if it could be made smaller.

Testing of InnoSwitch based boards for system level ESD has shown that any primary to secondary arcing must occur away from the InnoSwitch IC. Arcing across the device package, specifically to the drain pin causes destructive failure of the IC.

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In the figure above arcing would occur at point 1 for about 2% of applied ESD strikes. This is despite the spacing at (2) being smaller (5 mm) than point (1) (~7.2 mm). This result implies that the spark gap spacing must be at least 2 mm less than spacing from secondary traces and components to the InnoSwitch primary side.

Creepage and Clearance Requirements

All references are to IEC60950 2005 +A1:2009 +A2:2013

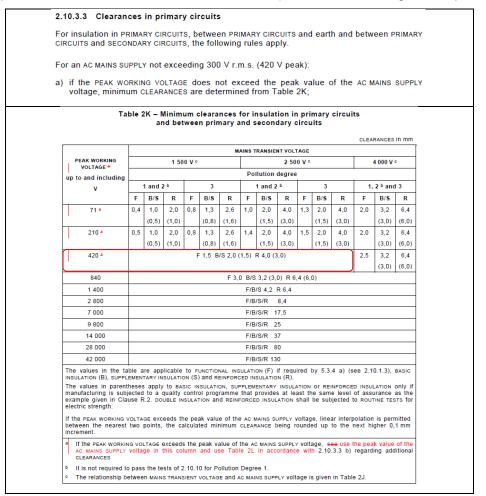
Requirements are determined according to IEC60950 Edition 2.2 (2013)

For a spark gap from primary AC to secondary the following assumptions were made:

- AC supply does not exceed 300 V
- The peak voltage across the spark gap during normal operation does not exceed the peak of the AC input voltage
- Pollution degree 2
- Spark gap is required to meet the requirements of reinforced insulation
- PCB falls into Group IIIb (CTI $100 \le$ CTI \le 175) (typical FR4 material)
- Operation to 2000 m above sea level

Clearance in primary circuits (2.10.3.3)

Table 2K provides values for reinforced insulation of **4 mm** (**3 mm** if electric strength test is performed)



Creepage in primary circuits (2.10.4.3)

Table 2N provides **5 mm** (2 x 2.5 mm) for Pollution degree 2, standard PCB material, **3.6 mm** (2 x 1.8 mm) for Pollution degree 2, high CTI PCB material and **8 mm** (2 x 4 mm) for Pollution degree 3.

	Pollution degree							
RMS WORKING VOLTAGE	1 ^a							
up to and including	Material Group							
V	I, II, Illa, Illb	1	Ш	IIIa, IIIb	I	Ш	IIIa, IIIb (see Note)	
10	0,08	0,4	0,4	0,4	1,0	1,0	1,0	
12,5	0,09	0,42	0,42	0,42	1,05	1,05	1,05	
16	0,1	0,45	0,45	0,45	1,1	1,1	1,1	
20	0,11	0,48	0,48	0,48	1,2	1,2	1,2	
32	0,125 0,14	0,5 0,53	0,5	0,5	1,25 1,3	1,25 1,3	1,25	
40	0,14	0,55	0,55	1,1	1,3	1,5	1,3	
50	0,18	0,55	0,85	1,2	1,5	1,0	1,9	
63	0,2	0,63	0,9	1,25	1,6	1,8	2,0	
80	0,22	0,67	0,9	1,3	1,7	1,9	2,1	
100	0,25	0,71	1,0	1,4	1,8	2,0	2,2	
125	0,28	0,75	1,05	1,5	1,9	2,1	2,4	
160	0,32	0,8	1,1	1,6	2,0	2,2	2,5	
200	0,42	1,0	1,4	2,0	2,5	2,8	3,2	
250	0,56	1,25	1,8	2,5	3,2	3,6	4,0	
320	0,75	1,6	2,2	3,2	4,0	4,5	5,0	
400 500	1,0	2,0	2,8	4,0	5,0	5,6	6,3	
630	1,3 1,8	2,5 3,2	3,6 4,5	5,0 6,3	6,3 8,0	7,1 9,0	8,0 10	
800	2,4	4.0	5.6	8.0	10	11	12.5	
0000	200	020						
ne values in the table apply to					(see 2 10	1.3) BAS	SIC INSULATION an	
SUPPLEMENTARY INSULATION.								
near interpolation may be use rounded up to the next highe values: not exceeding 0,5 mm, the spe for those exceeding 0,5 mm, th or REINFORCED INSULATION, th rounding off.	er specified incr ecified incremen ne specified incr	rement, o t is 0,01 rement is	mm; and 0,1 mm.	ue in the next	row belo	w, which	ever is lower. Fo	

PCB Material Feedback

Feedback from PCB vendor (<u>isaac@vectorfab.com</u>). Indicates that a small increase in PCB cost is incurred to use PCB material with a CTI >400, thereby meeting the material group II requirement

Hello Peter,

Regarding your question – Modified FR4 can be a number of variations, including FR4 High Temp, which is the most popular alternative to FR4. The increase in price is ~3% to 5% for High Temp and Halogen Free materials respectively. Both of these materials are available.

Best,

-isaac

Materials group	Tg	CTEz	ε,(1 MHz/1 GHz/10 GHz)	Proof volt- age	Surface resistance	Conduc- tive Track- ing Index (CTI)	Water absorp- tion	Cu adhe- sion
	°C	ppm/K	-	KV/mm	MΩ	v	%	N/mm
Standard FR4	125°C-140°C	<70	4,7/4,3/-	50	107	>200	0,06	1,5
Modified FR4	135°C-180°C	<55	4,6/4,2/-	45	107	>200	0,06	1,5
FR4 halogen free	150°C-170°C	<40	5,0/4,8/4,6	50	10 ⁸	>500	0,06	1,5
ВТ ероху	Approx. 200°C	<40	4,4/4,1/-	70	10 ⁸	>200	0,05	1,6
СЕ ероху	Approx. 250°C	<25	3,9/3,7/3,5	65	107	>200	0,05	1,6
Polyimide	220°C-260°C	<55	4,0/3,8/3,8	45	10 ⁸	>100	0,3	1
PTFE (pure)	200°C-230°C	<70	2,6/2,4/2,2	45	107	>600	0,04	1,3
RO3000	-	<40	3,0/2,8/2,6	30	107	>600	0,1	2,5
RO4000	Approx. 280°C	<45	3,3/3,0/2,8	30	10 ⁹	>600	0,04	1,0

Feedback from UL Consultant

1. Our product is classified as Pollution degree 2. This confirms our understanding and concurs with email discussions between you, Mike and Stefan last week.

2. The PCB is assumed to be Group IIIB. Again this is consistent with your original memo. Paul mentioned as long as the PCB manufacturer has their material listed and recognized with the higher CTI, we could use that to lower material group.

3. Clearance distance is specified in Table 2K and using a peak working voltage of 420V, the required reinforced insulation distance is 4mm. This is also consistent with your original memo.

4. Creepage distance which is the most relevant for our concerns is in Table 2N. Paul said that the nominal voltage of 240VRMS is used to determine the RMS working voltage between primary and secondary which is then used to determine the required creepage distance. He said that is it not customary to use 264VAC input for these measurements. He was clear that although the input voltage was 240VRMS, the working voltage can be much higher. He commented that during the safety qualification test the working voltage between two points bridging the isolation barrier is measured with a DVM. In our case he felt relatively safe to say that the since we are not measuring a switching node (like drain of primary HV MOSFET) or a transformer node, the working voltage would fall into the 250VRMS with Material group IIIB. With reinforced insulation the table entry is doubled and results in a creepage distance requirement of 5mm. Paul also commented that in the event the working voltage falls in between two of the entries in the table, linear interpolation is allowed.

Revision History:

Rev A. 18072013	First release
Rev B. 25072013	Second release – after feedback from UL consultant working voltage reduced to 250 V RMS